



**GENERAL PURPOSE THYRISTOR/DIODE MODULE**

**Features:**

- . Electrical insulation between chip and base plate, 2500V AC insulation
- . Compact structure
- . Excellent temperature characteristics and power cycling capability
- . Small size & light weight

**Typical application:**

- . AC / DC motor control
- . Various rectification power supplies
- . Frequency converter



**ELECTRICAL CHARACTERISTICS AND RATINGS**

Symbol	Parameter	Conditions	T <sub>j</sub> (°C)	Data			Unit
				Min	Typ	Max	
I <sub>T(AV)</sub>	Mean on-state current	Sine wave 180°, 50Hz Single side cooling, T <sub>c</sub> =85°C	125			1000	A
I <sub>T(RMS)</sub>	RMS on-state current		125			1570	A
V <sub>DRM</sub> V <sub>RRM</sub>	Repetitive peak off-state voltage Repetitive peak reverse voltage	V <sub>DRM</sub> &V <sub>RRM</sub> tp=10ms V <sub>DISM</sub> &V <sub>RSM</sub> =V <sub>DRM</sub> &V <sub>RRM</sub> +200V	25	800		1800	V
I <sub>DRM</sub>	Repetitive peak off-state current	V <sub>DM</sub> = V <sub>DRM</sub>	125			65	mA
I <sub>RRM</sub>	Repetitive peak reverse current	V <sub>RM</sub> = V <sub>RRM</sub>					
I <sub>TSM</sub>	Surge on-state current	10ms bottom width, half sine wave V <sub>R</sub> =0.6V <sub>RRM</sub>	125			16.0	KA
I <sup>2</sup> t	I squared t					1280	A <sup>2</sup> s*10 <sup>3</sup>
V <sub>TO</sub>	On-state threshold voltage		125			0.80	V
r <sub>T</sub>	Slope resistance					0.20	mΩ
V <sub>TM</sub>	Peak on-state voltage	I <sub>TM</sub> =3000A	25			1.60/1.30	V
dv/dt	Critical rise rate of off-state voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125			1000	V/μs
di/dt	Critical rise rate of on-state current	I <sub>TM</sub> =2000A Amplitude of gate trigger current I <sub>GM</sub> = 1.5A Gate current rise time t <sub>r</sub> ≤0.5 s	125			100	A/μs
I <sub>GT</sub>	Gate trigger current			30		100	mA
V <sub>GT</sub>	Gate trigger voltage			0.8		2.2	V
I <sub>H</sub>	Holding current	V <sub>O</sub> =12V, R <sub>L</sub> =3Ω	25	20		120	mA
I <sub>L</sub>	Latching Current					1000	mA
V <sub>GD</sub>	Gate non-trigger voltage	V <sub>DM</sub> =67%V <sub>DRM</sub>	125	0.2			V
R <sub>th(j-c)</sub>	Thermal impedance(junction to case)	180°sine wave, single side heat dissipation				0.034	°C /W
R <sub>th(c-h)</sub>	Thermal impedance(case to heatsink)	180°sine wave, single side heat dissipation				0.020	°C /W
V <sub>iso</sub>	Insulation voltage	50Hz,R.M.S,t=1 min,I <sub>iso</sub> :1mA(MAX)		2500			V
F <sub>m</sub>	Electrode mounting torque (M5)				14		N·m
	Base plate mounting torque (M6)				12		N·m
T <sub>stg</sub>	Storage temperature			-40		125	°C
W <sub>t</sub>	Weight				4050		g

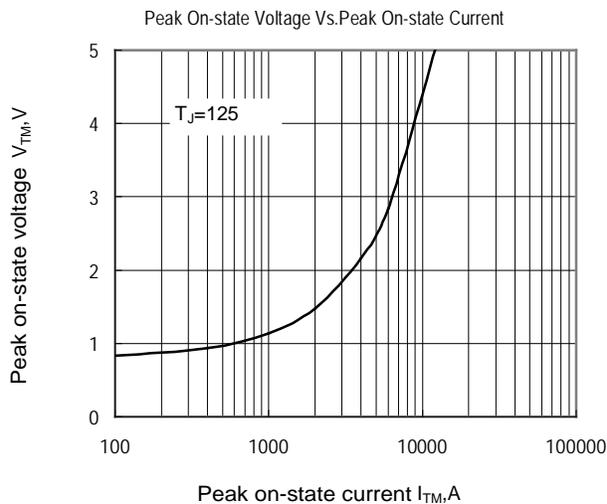


Fig.1 Forward Volt-ampere Characteristic Curve

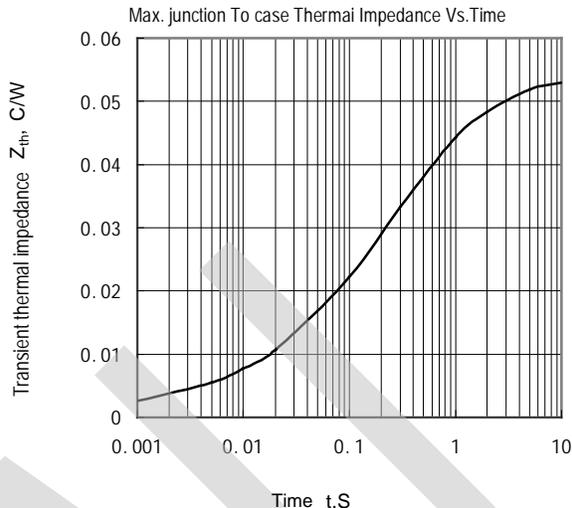


Fig.2 Transient Thermal Impedance of Junction to Case

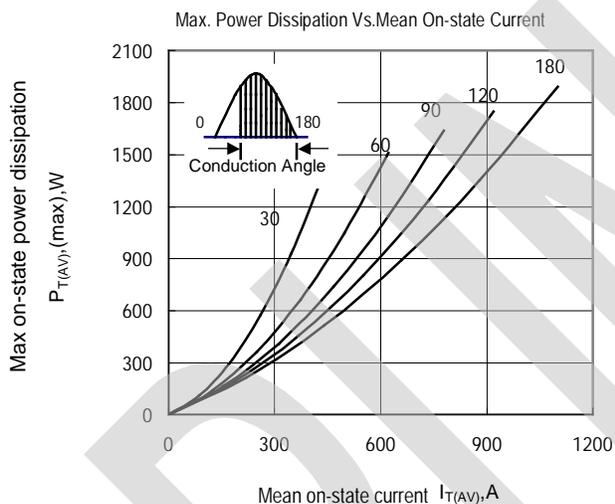


Fig.3 Max Power Dissipation Vs. Mean On-state Current

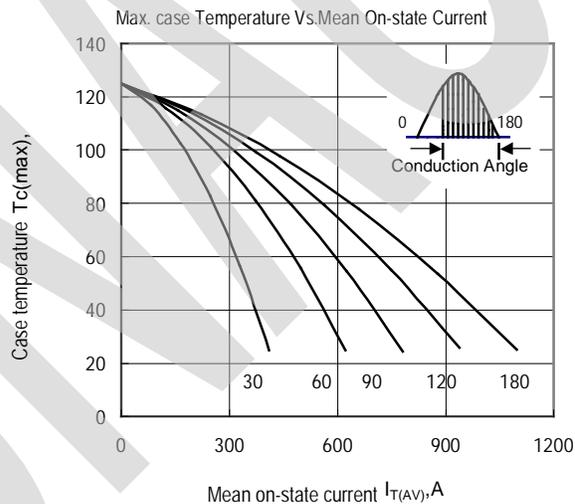


Fig.4 Max case Temperature Vs. Mean On-state Current

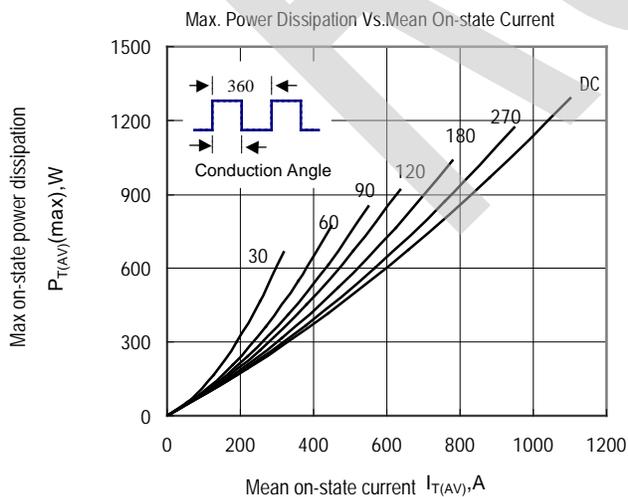


Fig.5 Max Power Dissipation Vs. Mean On-state Current

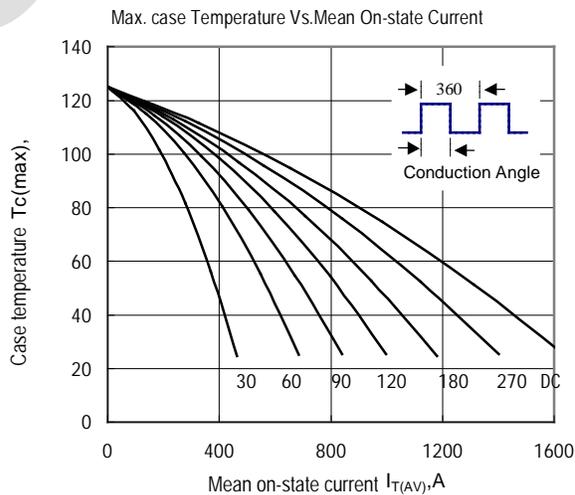


Fig.6 Max Case Temperature Vs. Mean On-state Current

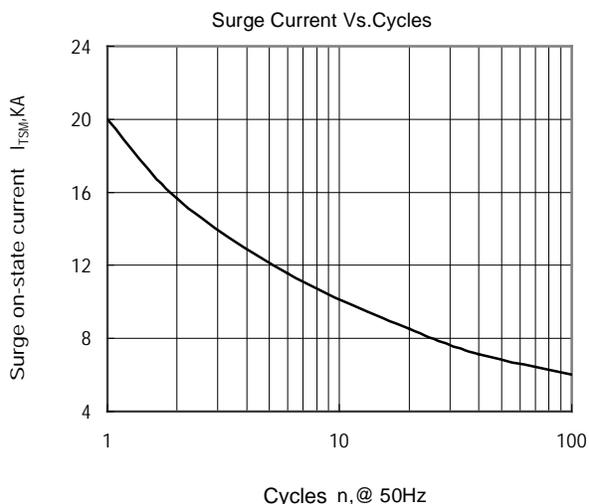


Fig.7 Surge Current Vs.Cycles

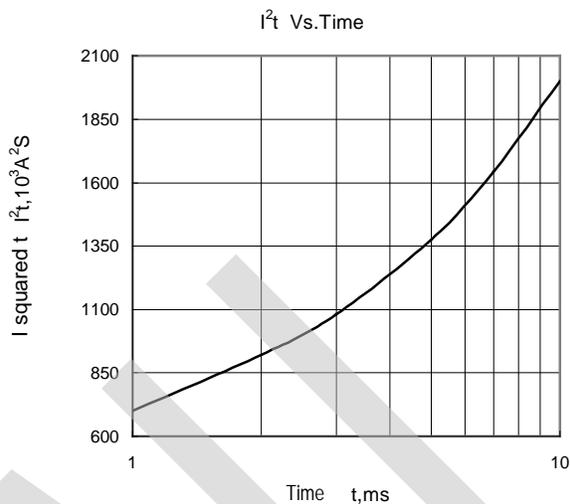


Fig.8  $I^2t$  Vs.Time

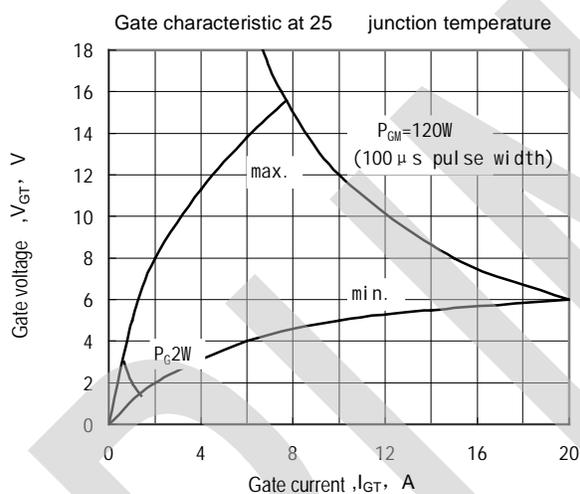


Fig.9 Gate Power Curve

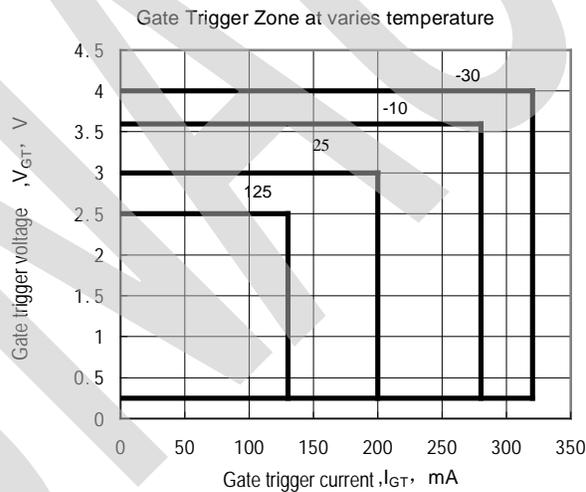


Fig.10 Gate Trigger Characteristic Curve

**OUTLINE**

